

Model : EBA31001 Series

BGA Heat Sink Specification

For 31x31 Chip set



1. Material : Al 6063

2. Dimension :

Foot print : 31x31mm

Height : 10 mm

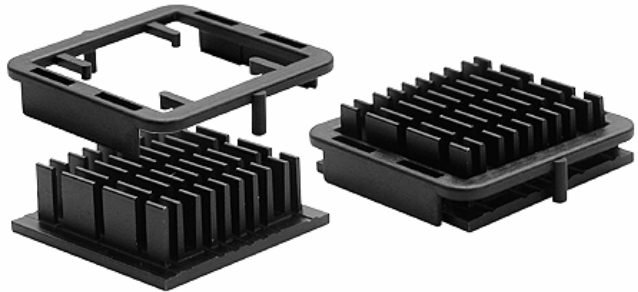
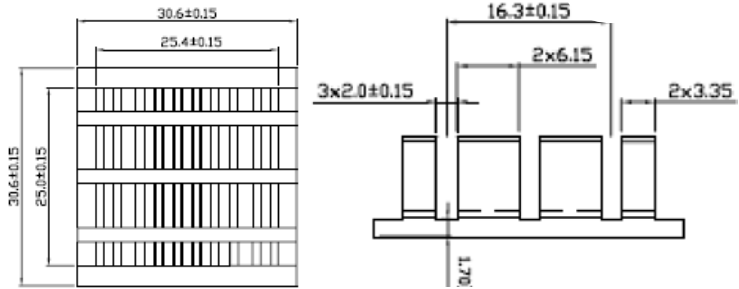
Base (thickness) : 1.7mm

3. Finish: Black Anodize

4. Accessory :

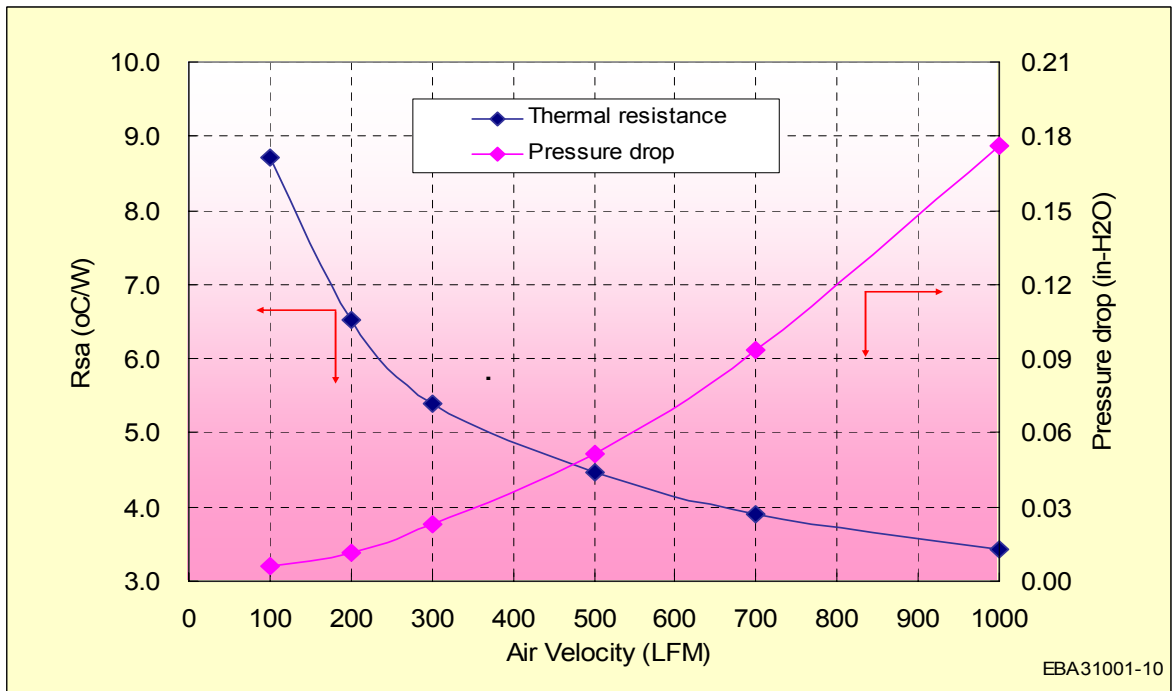
Clip : Plastic (UL94-V0)

Thermal pad : 8612I or others



Performance

Heat Source (LxW)	15x15
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EBA31001-10